

ETC5064/64-X ETC5067/67-X

SERIAL INTERFACE CODEC/FILTER WITH RECEIVE POWER AMPLIFIER

COMPLETE CODEC AND FILTERING SYS-TEM INCLUDING :

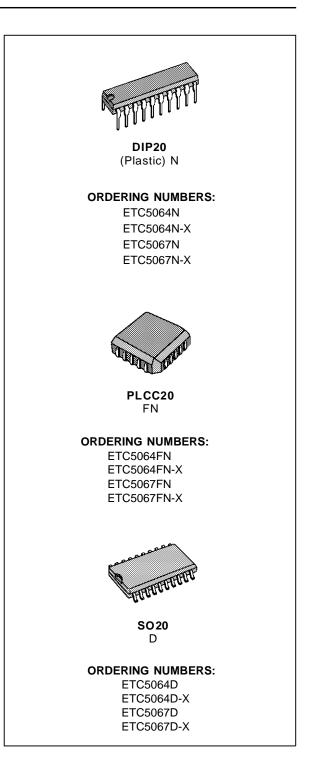
- Transmit high-pass and low-pass filtering.
- Receive low-pass filter with sin x/x correction.
- Active RC noise filter.
- μ-law or A-law compatible CODER and DE-CODER.
- Internal precision voltage reference.
- Serial I/O interface.
- Internal auto-zero circuitry.
- Receive push-pull power amplifiers.
- μ-LAW ETC5064
- A-LAW ETC5067
- MEETS OR EXCEEDS ALL D3/D4 AND CCITT SPECIFICATIONS.
- ±5 V OPERATION.
- LOW OPERATING POWER-TYPICALLY 70 mW
- POWER-DOWN STANDBY MODE-TYPICALLY
- AUTOMATIC POWER DOWN
- TTL OR CMOS COMPATIBLE DIGITAL INTER-FACES
- MAXIMIZES LINE INTERFACE CARD CIR-CUIT DENSITY
- 0°C TO 70°C OPERATION: ETC5064/67
- -40°C TO 85°C OPERATION: ETC5064-X/67-X

DESCRIPTION

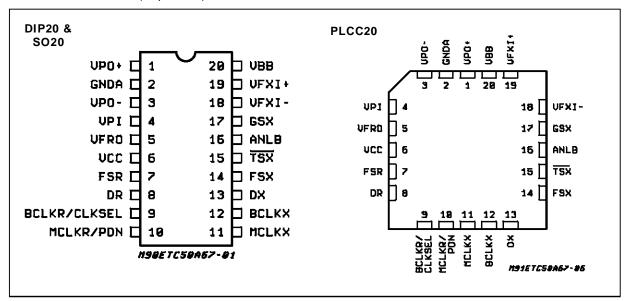
The ETC5064 (μ -law), ETC5067 (A-law) are monolithic PCM CODEC/FILTERS utilizing the A/D and D/A conversion architecture shown in the Block Diagrams and a serial PCM interface. The devices are fabricated using double-poly CMOS process.

Similar to the ETC505X family, these devices feature an additional Receive Power Amplifier to provide push-pull balanced output drive capability. The receive gain can be adjusted by means of two external resistors for an output level of up to \pm 6.6 V across a balanced 600 Ω load.

Also included is an Analog Loopback switch and \overline{TS}_X output.

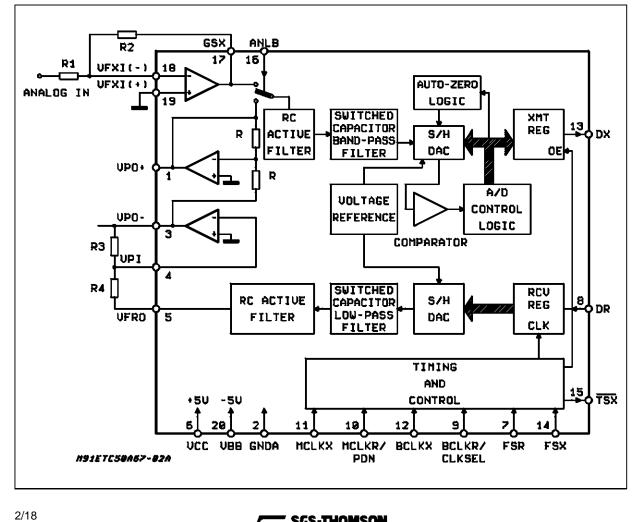


November 1994



PIN CONNECTIONS (Top views)

BLOCK DIAGRAM (ETC5064 - ETC5064-X - ETC5067 - ETC5067-X)



PIN DESCRIPTION

Name	Pin Type (*)	N	Description
VPO ⁺	0	1	The Non-inverting Output of the Receive Power Amplifier
GNDA	GND	2	Analog Ground. All signals are referenced to this pin.
VPO ⁻	0	3	The Inverting Output of the Receive Power Amplifier
VPI	I	4	Inverting Input to the Receive Power Amplifier. Also powers down both amplifiers when connected to $V_{\text{BB}}. \label{eq:BB}$
VF _R O	0	5	Analog Output of the Receive Filter.
Vcc	S	6	Positive Power Supply Pin. V _{CC} = +5V ±5%
FS _R	I	7	Receive Frame Sync Pulse which enable $BCLK_R$ to shift PCM data into D_R . FS _R is an 8KHz pulse train. See figures 1 and 2 for timing details.
D _R	Ι	8	Receive Data Input. PCM data is shifted into D_R following the FS_R leading edge
BCLK _R /CLKSEL	I	9	The bit Clock which shifts data into D_R after the FS _R leading edge. May vary from 64KHz to 2.048MHz. Alternatively, may be a logic input which selects either 1.536MHz/1.544MHz or 2.048MHz for master clock in synchronous mode and BCLK _X is used for both transmit and receive directions (see table 1). This input has an internal pull-up.
MCKL _R /PDN	I	10	Receive Master Clock. Must be 1.536MHz, 1.544MHz or 2.048MHz. May be asynchronous with MCLK _X , but should be synchronous with MCLK _X for best performance. When MCLK _R is connected continuously low, MCLK _X is selected for all internal timing. When MCLK _R is connected continuously high, the device is powered down.
MCLK _X	I	11	Transmit Master Clock. Must be 1.536MHz, 1.544MHz or 2.048MHz. May be asynchronous with MCLK _R .
BCLK _X	Ι	12	The bit clock which shifts out the PCM data on D_X . May vary from 64KHz to 2.048MHz, but must be synchronous with MCLK _X .
Dx	0	13	The TRI-STATE®PCM data output which is enabled by FS _X .
FS _X	Ι	14	Transmit frame sync pulse input which enables $BCLK_X$ to shift out the PCM data on D_X . FS _X is an 8KHz pulse train. See figures 1 and 2 for timing details.
TS _X	0	15	Open drain output which pulses low during the encoder time slot. Must to be grounded if not used.
ANLB	I	16	Analog Loopback Control Input. Must be set to logic '0' for normal operation. When pulled to logic '1', the transmit filter input is disconnected from the output of the transmit preamplifier and connected to the VPO ⁺ output of the receive power amplifier.
GS _X	0	17	Analog output of the transmit input amplifier. Used to set gain externally.
VF _X I ⁻	I	18	Inverting input of the transmit input amplifier.
VF_XI^+	I	19	Non-inverting input of the transmit input amplifier.
V _{BB}	S	20	Negative Power Supply Pin. $V_{BB} = -5V \pm 5\%$

(*) I: Input, O: Output, S: Power Supply. TRI-STATE $\ensuremath{\mathbb{R}}$ is a trademark of National Semiconductor Corp.



FUNCTIONAL DESCRIPTION

POWER-UP

When power is first applied, power-on reset circuitry initializes the device and places it into the powerdown mode. All non-essential circuits are deactivated and the D_X and VF_RO outputs are put in high impedancestates. To power-up the device, a logical low level or clock must be applied to the MCLK_R/PDN pin and FS_X and/or FS_R pulses must be present. Thus 2 power-down control modes are available. The first is to pull the MCLK_R/PDN pin high; the alternative is to hold both FS_X and FS_R inputs continuously low. The device will power-down approximately 2 ms after the last FS_X pulse. The TRI-STATE PCM data output, D_X, will remain in the high impedance state until the second FS_X pulse.

SYNCHRONOUS OPERATION

For synchronous operation, the same master clock and bit clock should be used for both the transmit and receive directions. In this mode, a clock must be applied to MCLK_X and the MCLK_R/PDN pin can be used as a power-down control. A low level on MCLK_R/PDN powers up the device and a high level powers down the device. In either case, MCLKX will be selected as the master clock for both the transmit and receive circuits. A bit clock must also be applied to BCLK_X and the BCL_R/CLKSEL can be used to select the proper internal divider for a master clock of 1.536 MHz, 1.544 MHz or 2.048 MHz. For 1.544 MHz operation, the device automatically compensates for the 193 rd clock pulse each frame.

With a fixed level on the BCLK_R/CKSEL pin, BCLK_X will be selected as the bit clock for both the transmit and receive directions. Table 1 indicates the frequencies of operation which can be selected, depending on the state of BCLK_R/CLKSEL. In this synchronous mode, the bit clock, BCLK_X, may be from 64 kHz to 2.048 MHz, but must be synchronous with MCLK_X.

Table 1: Selection of Master	r Clock Frequencies.
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BCLKR/CLKSEL	Master Clock Frequency Selected				
BULKINGLKOLL	ETC5067 ETC5067-X	ETC5064 ETC5064-X			
Clocked	2.048MHz	1.536MHz or 1.544MHz			
0	1.536MHz or 1.544MHz	2.048MHz			
1 (or open circuit)	2.048MHz	1.536MHz or 1.544MHz			

Each FS_X pulse begins the encoding cycle and the PCM data from the previous encode cycle is shift out of the enabled D_X output on the positive edge of BCLK_X. After 8 bit clock periods, the TRISTATE D_X output is returned to a high impedance state. With an FS_R pulse, PCM data is latched via the D_R input on the negative edge of BCLK_X (or on BCKL_R if running). FS_X and FS_R must be synchronous with MCLKX/_R.

ASYNCHRONOUS OPERATION

For asynchronous operation, separate transmit and receive clocks may be applied. MCLK_X and MCLK_R must be 2.048 MHz for the ETC5067 or 1.536 MHz, 1.544 MHz for the ETC5064, and need not be synchronous. For best transmission performance, however, MCLK_R should be synchronous with MCLK_X, which is easily achieved by applying only static logic levels to the MCLK_R/PDN pin. This will automatically connect MCLK_X to all internal MCLK_R functions (see pin description). For 1.544 MHz operation, the device automatically compensates for the 193rd clock pulse each frame. FSx starts each encoding cycle and must be synchronous with MCLK_X and BCLK_X. FS_R starts each decoding cycle and must be synchronous with BCLK_R. BCLK_R must be a clock, the logic levels shown in Table 1 are not valid in asynchronous mode. BCLK_X and BCLK_R may operate from 64kHz to 2.048 MHz.

SHORT FRAME SYNC OPERATION

The device can utilize either a short frame sync pulse or a long frame sync pulse. Upon power initialization, the device assumes a short frame mode. In this mode, both frame sync pulses. FS_X and FS_R , must be one bit clock period long, with timing relationships specified in figure 2. With FS_X high during a falling edge of BCLK_R, the next rising edge of BCLKx enables the Dx TRI-STATE output buffer. which will output the sign bit. The following seven rising edges clock out the remaining seven bits, and the next falling edge disables the D_X output. With FSR high during a falling edge of BCLKR (BCLKx in synchronous mode), the next falling edge of BCLK_R latches in the sign bit. The following seven falling edges latch in the seven remaining bits. Both devices may utilize the short frame sync pulse in synchronous or asynchronous operating mode.

LONG FRAME SYNC OPERATION

To use the long frame mode, both the frame sync pulses, FS_X and FS_R , must be three or more bit clock periods long, with timing relationships specified in figure 3. Based on the transmit frame sync FS_X , the device will sense whether short or long frame sync



pulses are being used. For 64 kHz operation, the frame sync pulses must be kept low for a minimum of 160 ns (see Fig 1). The D_X TRI-STATE output buffer is enabled with the rising edge of FSx or the rising edge of BCLK_X, whichever comes later, and the first bit clocked out is the sign bit. The following seven BCLK_X rising edges clock out the remaining seven bits. The D_X output is disabled by the falling BCLK_X edge following the eighth rising edge, or by FS_X going low, whichever comes later. A rising edge on the receive frame sync pulse, FS_R, will cause the PCM data at D_R to be latched in on the next eight falling edges of BCLK_R (BCLK_x in synchronous mode). Both devices may utilize the long frame sync pulse in synchronous or asynchronous mode.

TRANSMIT SECTION

The transmit section input is an operational amplifier with provision for gain adjustment using two external resistors, see figure 4. The low noise and wide bandwidth allow gains in excess of 20 dB across the audio passband to be realized. The op amp drives a unity gain filter consisting of RC active pre-filter, followed by an eighth order switched-capacitor bandpass filter directly drives the encoder sampleand-hold circuit. The A/D is of companding type according to A-law (ETC5067 and ETC5067-X) or $\mu\text{-}$ law (ETC5064 and ETC5064-X) coding conventions. A precision voltage reference is trimmed in manufacturing to provide an input over load (t_{MAX}) of nominally 2.5V peak (see table of Transmission Characteristics). The FS_X frame sync pulse controls the sampling of the filer output, and then the successive-approximation encoding cycle begins. The 8-bit code is then loaded into a buffer and shifted out through D_X at the next FS_X pulse, the total encoding delay will be approximately 165 µs (due to the transmit filter) plus 125µs (due to encoding delay), which totals 290µs. Any offset voltage due to the filters or comparator is cancelled by sign bit integration.

The receive section consist of an expanding DAC which drives a fifth order switched-capacitor low

RECEIVE SECTION

which drives a fifth order switched-capacitor low pass filter clocked at 256kHz. The decoder is A-law (ETC5067 and ETC5067-X) or µ-law (ETC5064 and ETC5064-X) and the 5 th order low pass filter corrects for the sin x/x attenuation due to the 8kHz sample and hold. The filter is then followed by a 2 nd order RC active post-filter and power amplifier capable of driving a 600Ω load to a level of 7.2dBm. The receive section is unity-gain. Upon the occurence of FS_R , the data at the D_R input is clocked in on the falling edge of the next eight BCLKR (BCKL_x) periods. At the end of the decoder time slot, the decoding cycle begins, and 10µs later the decoder DAC output is updated. The total decoder delay is about10µs (decoder up-date) plus 110µs (filter delay) plus 62.5µs (1/2 frame), which gives approximately 180us.

RECEIVE POWER AMPLIFIERS

Two inverting mode power amplifiers are provided for directly driving a matched line interface transformer. The gain of the first power amplifier can be adjusted to boost the \pm 2.5V peak output signal from the receive filter up \pm 3.3V peak into an unbalanced 300Ω load, or $\pm 4.0V$ into an unbalanced $15k\Omega$ load. The second power amplifier is internally connected in unity-gain inverting mode to give 6dB of signal gain for balanced loads. Maximum power transfer to a 600 Ω subscriber line termination is obtained by differientially driving a balanced transformer with a $\sqrt{2}$: 1 turns ratio, as shown in figure 4. A total peak power of 15.6dBm can be delivered to the load plus termination. Both power amplifier can be powered down independently from the PDN input by connecting the VPI input to V_{BB} saving approximately 12 mW of power.

Symbol	Parameter	Value	Unit
V _{CC}	V _{CC} to GNDA	7	V
V _{BB}	V _{BB} to GNDA	-7	V
VIN, VOUT	Voltage at any Analog Input or Output	V _{CC} +0.3 to V _{BB} -0.3	V
	Voltage at any Digital Input or Output	V _{CC} +0.3 to GNDA -0.3	V
T _{oper}	Operating Temperature Range: ETC5064/67 ETC5064-X/67-X	-25 to +125 -40 to +125	°C ℃
T _{stg}	Storage Temperature Range	-65 to +150	°C
	Lead Temperature (soldering, 10 seconds)	300	°C

ABSOLUTE MAXIMUM RATINGS



ELECTRICAL OPERATING CHARACTERISTICS

 $V_{CC} = 5.0V \pm 5\%$, $V_{BB} = -5V \pm 5\%$, GNDA = 0V, $T_A = 0^{\circ}C$ to 70°C (ETC5064-X/67-X: $T_A = -40^{\circ}C$ to 85°), unless otherwise noted; typical characteristics specified at $V_{CC} = 5.0V$, $V_{BB} = -5.0V$, $T_A = 25^{\circ}C$; all signals are referenced to GNDA.

DIGITAL INTERFACE (All devices)

Symbol	Parameter		Min.	Тур.	Max.	Unit
VIL	Input Low Voltage				0.6	V
VIH	Input High Voltage		2.2			V
Vol	Output Low Voltage $I_L = 3.2 \text{ mA}$ $I_L = 3.2 \text{ mA}$, Open Drain	Dx TSx			0.4 0.4	V V
V _{OH}	Output High Voltage IH = 3.2 mA	Dx	2.4			V
IIL	Input Low Current (GNDA $\leq V_{IN} \leq V_{IL}$)all digital inputs Except BCLK _R		- 10		10	μΑ
Ін	Input High Current (VIH ≤ VIN ≤ Vcc) Except ANLB		- 10		10	μA
l _{OZ}	Output Current in High Impedance State (TRI-STATE) (GNDA $\leq V_0 \leq V_{CC}$)	D _X	- 10		10	μA

ANALOG INTERFACE WITH TRANSMIT INPUT AMPLIFIER (all devices)

Symbol	Parameter		Min.	Тур.	Max.	Unit
Ι _Ι ΧΑ	Input Leakage Current (- $2.5 V \le V \le + 2.5 V$)	VFxI ⁺ or VFxI ⁻	- 200		200	nA
R _I XA	Input Resistance (- $2.5 V \le V \le + 2.5 V$)	VF_XI^+ or VF_XI^-	10			MΩ
R _O XA	Output Resistance (closed loop, unity gain)			1	3	Ω
R _L XA	Load Resistance	GS _X	10			kΩ
C _L XA	Load Capacitance	GS _X			50	рF
VoXA	Output Dynamic Range ($R_L \ge 10 \text{ k}\Omega$)	GS _X	- 2.8		+2.8	V
A _V XA	Voltage Gain (VF _X I ⁺ to GS _X)		5000			V/V
F∪XA	Unity Gain Bandwidth		1	2		MHz
V _{OS} XA	Offset Voltage		- 20		20	mV
V _{CM} XA	Common-mode Voltage		- 2.5		2.5	V
CMRRXA	Common-mode Rejection Ratio		60			dB
PSRRXA	Power Supply Rejection Ratio		60			dB

ANALOG INTERFACE WITH RECEIVE FILTER (all devices)

Symbol	Parameter	Min.	Тур.	Max.	Unit
RoRF	Output Resistance VF _R O		1	3	Ω
R∟RF	Load Resistance (VF _R O = \pm 2.5 V)	10			kΩ
C∟RF	Load Capacitance			25	рF
VOS _R O	Output DC Offset Voltage	- 200		200	mV



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ELECTRICAL OPERATING CHARACTERISTICS (Continued)

ANALOG INTERFACE WITH POWER AMPLIFIERS (all devices)

Symbol	Parameter	Min.	Тур.	Max.	Unit
IPI	Input Leakage Current (- $1.0 \text{ V} \leq \text{VPI} \leq 1.0 \text{ V}$)	- 100		100	nA
RIPI	Input Resistance (– $1.0 \le VPI \le 1.0 V$)	10			MΩ
VIOS	Input Offset Voltage	- 25		25	mV
ROP	Output Resistance (inverting unity-gain at VPO ⁺ or VPO ⁻)		1		Ω
Fc	Unity–gain Bandwidth, Open Loop (VPO ⁻)		400		kHz
C∟P	Load Capacitance (VPO ⁺ or VPO ⁻ to GNDA) $R_L \ge 1500 \Omega$ $R_L = 600 \Omega$ $R_L = 300 \Omega$			100 500 1000	pF
GAp⁺	Gain VPO ⁻ to VPO ⁺ to GNDA, Level at VPO ⁻ = 1.77 Vrms (+ 3 dBmO)		- 1		V/V
PSRRp	Power Supply Rejection of V_{CC} or V_{BB} (VPO ⁻ connected to VPI) 0 kHz - 4 kHz 0 kHz - 50 kHz	60 36			dB

POWER DISSIPATION (all devices)

Symbol	Parameter	Min.	Тур.	Max.	Unit
I _{CC} 0	Power-down Current at ETC6064/67 ETC5064-X/67-X		0.5 0.5	1.5	mA mA
I _{BB} O	Power-down Current at ETC6064/67 ETC5064-X/67-X		0.05 0.05	0.3 0.4	mA mA
I _{CC} 1	Active Current at ETC6064/67 ETC5064-X/67-X		7.0 7.0	10.0 12.0	mA mA
I _{BB} 1	Active Current at ETC6064/67 ETC5064-X/67-X		7.0 7.0	10.0 12.0	mA mA

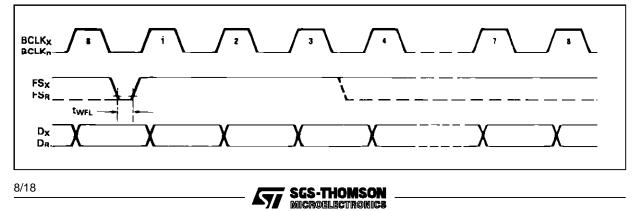


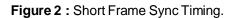
AII TIMING SPECIFICATIONS

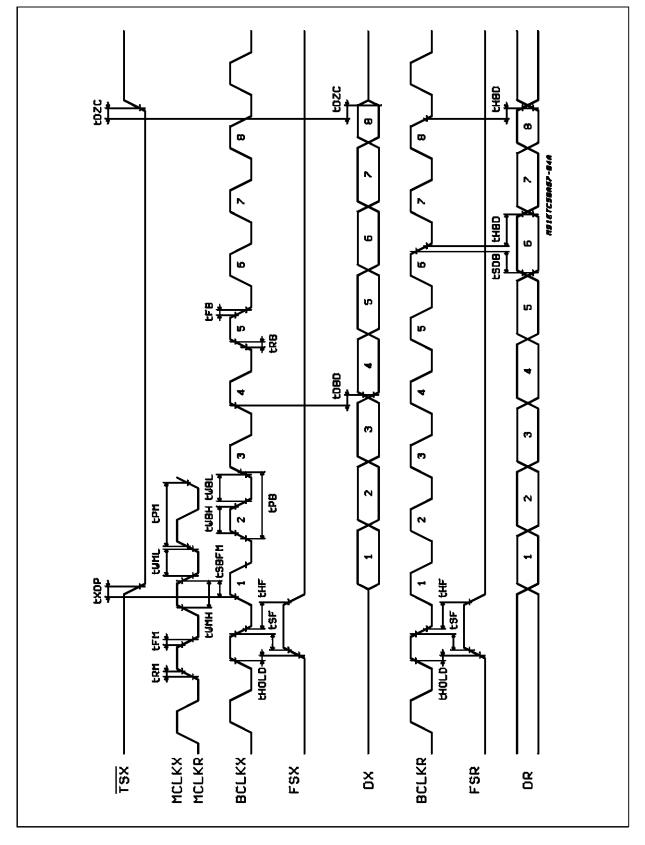
Symbol	Parameter	Min.	Тур.	Max.	Unit
1/t _{PM}	Frequency of master clocks $MCLK_X$ and $MCLK_R$ Depends on the device used and the $BCLK_R/CLKSEL$ Pin		1.536 2.048 1.544		MHz
twмн	Width of Master Clock High MCLK _X and MCLK _R	160			ns
twmL	Width of Master Clock Low MCLK _X and MCLK _R	160			ns
t _{RM}	Rise Time of Master Clock MCLK _X and MCLK _R			50	ns
t _{FM}	Fall Time of Master Clock MCLK _X and MCLK _R			50	ns
t _{PB}	Period of Bit Clock	485	488	15.725	ns
t _{wвн}	Width of Bit Clock High ($V_{IH} = 2.2 \text{ V}$)	160			ns
t _{WBL}	Width of Bit Clock Low ($V_{IL} = 0.6 V$)	160			ns
t _{RB}	Rise Time of Bit Clock (t _{PB} = 488 ns)			50	ns
t _{FB}	Fall Time of Bit Clock (t _{PB} = 488 ns)			50	ns
t SBFM	Set-up time from BCLK _X high to MCLK _X falling edge. (first bit clock after the leading edge of FS_X)	100			ns
t _{HBF}	Holding Time from Bit Clock Low to the Frame Sync (long frame only)	0			ns
t _{SFB}	Set-up Time from Frame Sync to Bit Clock (long frame only)	80			ns
t _{HBFI}	$\begin{array}{llllllllllllllllllllllllllllllllllll$	100			ns
t _{DZF}	Delay Time to valid data from FS_X or $BCLK_X$, whichever comes later and delay time from FSX to data output disabled ($C_L = 0 \text{ pF}$ to 150 pF)	20		165	ns
t _{DBD}	Delay Time from BCLK _X high to data valid (load = 150 pF plus 2 LSTTL loads)	0		150	ns
t _{DZC}	Delay Time from BCLK _X low to data output disabled	50		165	ns
t _{SDB}	Set-up Time from D _R valid to BCLK _{R/X} low	50			ns
t _{HBD}	Hold Time from BCLK _{R/X} low to D _R invalid	50			ns
tHOLD	Holding Time from Bit Clock High to Frame Sync (short frame only)	0			ns
tsF	Set-up Time from FS _{X/R} to BCLK _{X/R} Low (short frame sync pulse) - Note 1	80			ns
t _{HF}	Hold Time from BCLK _{X/R} Low to FS _{X/R} Low (short frame sync pulse) - Note 1	100			ns
t _{XDP}	Delay Time to TS _X low (load = 150 pF plus 2 LSTTI loads)			140	ns
t _{WFL}	Minimum Width of the Frame Sync Pulse (low level) (64 bit/s operating mode)	160			ns

Note : 1.For short frame sync timing. FS_X and FS_R must go high while their respective bit clocks are high.





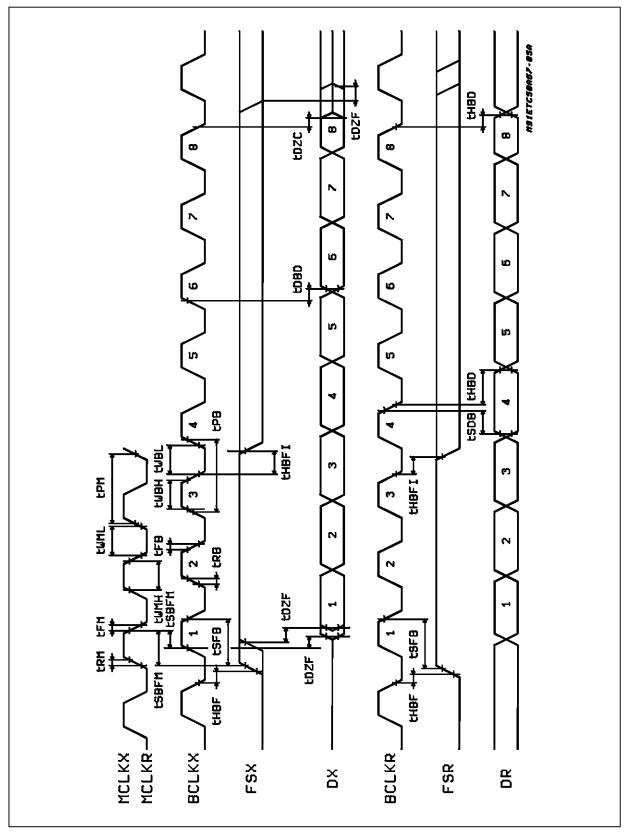




SGS-THOMSON MICROELECTRONICS

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Figure 3 : Long Frame Sync Timing.





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TRANSMISSION CHARACTERISTICS

(all devices) $T_A = 0^{\circ}$ C to 70°C (ETC5064-X/67-X: $T_A = -40^{\circ}$ C to 85°), $V_{CC} = 5V \pm 5\%$, $V_{BB} = -5V \pm 5\%$, GNDA = 0V, f = 1.02kHz, $V_{IN} = 0$ dBm0 transmit input amplifier connected for unity–gain non–inverting. (unless otherwise specified).

AMPLITUDE RESPONSE

Symbol	Parameter	Min.	Тур.	Max.	Unit
	Absolute Levels - Nominal 0 dBm0 is 4 dBm (600Ω). 0 dBm0		1.2276		Vrms
t _{MAX}	Max Overload Level ETC5067 3.14 dBm0 ETC5064 3.17 dBm0 ETC5064		2.492 2.501		VPK
G _{XA}	Transmit Gain, Absolute ($T_A = 25^{\circ}C$, $V_{CC} = 5V$, $V_{BB} = -5V$) Input at GS _X = 0dBm0 at 1020Hz	-0.15		0.15	dB
GXR	Transmit Gain, Relative to GXA f = 16Hz f = 50Hz f = 60Hz f = 180Hz f = 200Hz f = 300Hz -3000Hz f = 3200Hz (ETC5064-X/67-X) f = 3300Hz f = 3400Hz f = 4000Hz f = 4600Hz and up, measure response from oHz to 4000Hz	- -2.8 -1.8 -0.15 -0.35 -0.35 -0.7		-40 -30 -26 -0.2 -0.1 0.15 0.20 0.05 0 -14 -32	dB
G _{XAT}	Absolute Transmit Gain Variation with Temperature $T_A = 0^{\circ}C$ to +70°C $T_A = -40^{\circ}C$ to +85°C (ETC5064-X/67-X)	-0.1 -0.15		0.1 0.15	dB
G _{XAV}	Absolute Transmit Gain Variation with Supply Voltage (V _{CC} = 5V \pm 5%, V _{BB} = -5V \pm 5%)	-0.05		0.05	dB
Gxrl	Transmit Gain Variation with Level Sinusolidal Test Method Reference Level = -10dBm0 VF_XI^+ = -40dBm0 to +3dBm0 VF_XI^+ = -50dBm0 to -40dBm0 VF_XI^+ = -55dBm0 to -50dBm0	-0.2 -0.4 -1.2		0.2 0.4 1.2	dB
G _{RA}	Receive Gain, Absolute ($T_A = 25^{\circ}C$, $V_{CC} = 5V$, $V_{BB} = -5V$) Input = Digital Code Sequence for 0dBm0 Signal at 1020Hz	-0.15		0.15	dB
G _{RR}	Receive Gain, Relative to G_{RA} f = 0Hz to 3000Hz f = 3200Hz (ETC5064-X/67-X) f = 3300Hz f = 3400Hz f = 4000Hz	-0.15 -0.35 -0.35 -0.7		0.15 0.20 0.05 0 -14	dB
Grat	Absolute Receive Gain Variation with Temeperature $T_A = 0^{\circ}C$ to +70°C $T_A = -40^{\circ}C$ to +85°C (ETC5064-X/67-X)	-0.1 -0.15		0.1 0.15	dB
Grav	Absolute Receive Gain Variation with Supply Voltage (V _{CC} = 5V \pm 5%, V _{BB} = -5V \pm 5%)	-0.05		0.05	dB
G _{RRL}	Receive Gain Variation with Level Sinusoidal Test Method; Reference Input PCM code corresponds to an ideally encoded -10dBm0 signal PCM level = -40dBm0 to +3dBm0 PCM level = -50dBm0 to -40dBm0 PCM level = -55dBm0 to -50dBm0	-0.2 -0.4 -1.2		0.2 0.4 1.2	dB
V _{RO}	Receive Filter Output at $VF_ROR_L = 10K\Omega$	-2.5		2.5	V



TRANSMISSION CHARACTERISTICS (continued).

ENVELOPE DELAY DISTORTION WITH FREQUENCY

Symbol	Parameter	Min.	Тур.	Max.	Unit
D _{XA}	Transmit Delay, Absolute (f = 1600 Hz)		290	315	μs
D _{XR}	Transmit Delay, Relative to D_{XA} f = 500 Hz-600 Hz f = 600 Hz-800 Hz f = 800 Hz-1000 Hz f = 1000 Hz-1600 Hz f = 1600 Hz-2600Hz f = 2600 Hz-2800 Hz f = 2800 Hz-3000 Hz		195 120 50 20 55 80 130	220 145 75 40 75 105 155	μs
D _{RA}	Receive Delay, Absolute (f = 1600 Hz)		180	200	μs
D _{RR}	Receive Delay, Relative to D _{RA} f = 500 Hz-1000 Hz f = 1000 Hz-1600 Hz f = 1600 Hz-2600 Hz f = 2600 Hz-2800 Hz f = 2800 Hz-3000 Hz	- 40 - 30	- 25 - 20 70 100 145	90 125 175	μs

NOISE

Symbol	Parameter	Min.	Тур.	Max.	Unit
Nxp	Transmit Noise, P Message (A-LAW, VFxI ⁺ = 0 V) Weighted 1) ETC5064 ETC5064-X		- 74 - 74	- 69 - 67	dBm0p dBm0p
N _{RP}	Receive Noise, P Message Weighted (A-LAW, PCM Code Equals Positive Zero)		- 82	- 79	dBm0p
N _{XC}	Transmit Noise, C Message Weighted (μ -LAW, VFxI ⁺ = 0 V) ETC5064 ETC5064-X		12 12	15 16	dBrnC0 dBrnC0
N _{RC}	Receive Noise, C Message Weighted (μ-LAW, PCM Code Equals Alternating Positive and Negative Zero)		8	11	dBrnC0
N _{RS}	Noise, Single Frequency $f = 0 \text{ kHz}$ to 100 kHz, Loop around Measurement, VFxI ⁺ = 0 V			- 53	dBm0
PPSR _X	Positive Power Supply Rejection, Transmit (note 2) $V_{CC} = 5.0 V_{DC} + 100 \text{ mVrms}$, f = 0 kHz-50 kHz	40			dBp
NPSR _X	Negative Power Supply Rejection, Transmit (note 2) $V_{BB} = 5.0 V_{DC} + 100 \text{ mVrms}, f = 0 \text{ kHz}-50 \text{ kHz}$	40			dBp
PPSR _R	$\begin{array}{l} \mbox{Positive Power Supply Rejection, Receive (PCM code equals positive zero, $V_{CC} = 5.0 V_{DC} + 100 mVrms)$ f = 0 Hz-4000Hz $A LAW $$ $$ $$ $$ $$ $$ $$ $$ $$ $$ $$ $$ $$	40 40 40 36			dBp dBc dB dB
NPSR _R	$\begin{array}{l} \mbox{Negative Power Supply Rejection, Receive (PCM code equals positive zero, $V_{BB} = -5.0 \ V_{DC} + 100 \ mVrms$)$ \\ \mbox{f} = 0 \ Hz-4000 \ Hz & A \ LAW \\ & \mu \ LAW \\ \mbox{f} = 4 \ \mbox{Hz-25 \ \mbox{kHz}} \\ \mbox{f} = 25 \ \mbox{kHz-50 \ \mbox{kHz}} \end{array}$	40 40 40 36			dBp dBc dB dB
SOS	Spurious out-of-band Signals at the Channel Output 0 dBm0, 300 Hz-3400 Hz input PCM applied at D_R 4600 Hz-7600 Hz 7600 Hz-8400 Hz 8400 Hz-100,000 Hz			-32 -40 -32	dB dB dB





TRANSMISSION CHARACTERISTICS (continued).

DISTORTION

Symbol	Parameter		Min.	Тур.	Max.	Unit
STD _X	Signal to Total Distortion (sinusoidal test method)					
or						
STD _R	Transmit or Receive Half-channel				dBp	
	Level = 3.0 dBm0		33			(ALAW)
	= 0 dBm0 to - 30 dBm0		36			
	= - 40 dBm0	KMT	29			dBc
	R	CV	30			(µLAW)
	= - 55 dBm0	KMT	14			
	R	RCV	15			
SFD _X	Single Frequency Distortion, Transmit ($T_A = 25^{\circ}C$)				- 46	dB
SFD _R	Single Frequency Distortion, Receive ($T_A = 25^{\circ}C$)				- 46	dB
IMD	Intermodulation Distortion				- 41	dB
	Loop Around Measurement, $VF_XI^+ = -4 \text{ dBm0}$ to					
	- 21 dBm0, two Frequencies in the Range 300 Hz-3400 Hz					

CROSSTALK

Symbol	Parameter	Min.	Тур.	Max.	Unit
CT _{X-R}	Transmit to Receive Crosstalk, 0dBm0 Transmit f = 300 Hz-3400 Hz, D _R = Steady PCM Code ETC5064/67 ETC5064-X/67-X		- 90	- 75 - 65	dB dB
CT _{R-X}	$\label{eq:receive} \begin{array}{llllllllllllllllllllllllllllllllllll$		- 90	- 70 - 65	dB dB

POWER AMPLIFIERS

Symbol	Parameter	Min.	Тур.	Max.	Unit
V _{OL}	Maximum 0 dBm0 Level for Better than \pm 0.1 dB Linearity Over the Range 10 dBm0 to + 3 dBm0				Vrms
	(balanced load, R_L connected between VPO ⁺ and VPO ⁻)				
	$R_L = 600 \Omega$	33			
	R _L = 1200 Ω	3.5			
	$R_L = 30 \text{ k}\Omega$	4.0			
S/D _P	Signal/Distortion $R_L = 600 \Omega$, 0 dBm0	50			dB

Notes: 1. Measured by extrapolation from the distortion test results.
2. PPSRX, NPSRX, CTR-X measured with a -50dBm0 activating signal applied at VFxI⁺

ENCODING FORMAT AT D_X OUTPUT

	A-Law (Including even bit inversion)	μLaw
V_{IN} (at GS_X) = + Full-scale	10101010	1000000
V_{IN} (at GS _X) = 0 V	1 1 0 1 0 1 0 1	1 1 1 1 1 1 1 1
	0 1 0 1 0 1 0 1	0 1 1 1 1 1 1 1
V_{IN} (at GS_X) = - Full-scale	0 0 1 0 1 0 1 0	0 0 0 0 0 0 0 0



APPLICATION INFORMATION

POWER SUPPLIES

While the pins at the ETC506X family are well protected against electrical misure, it is recommended that the standard CMOS practice be followed, ensuring that ground is connected to the device before any other connections are made. In applications where the printed circuit board may be plugged into a "hot" socket with power and clocks already present, an extra long ground pin in the connector should be used.

All ground connections to each device should meet at a common point as close as possible to the GNDA pin. This minimizes the interaction of ground return currents flowing through a common bus impedance. 0.1μ F supply decoupling capacitors should be connected from this common ground point to VCC and VBB as close to the device as possible.

For best performance, the ground point of each CODEC/FILTER on a card should be connected to a common card ground in star formation, rather than via a ground bus. This common ground point should be decoupled to VCC and VBB with 10μ F capacitors.

For best performance, \overline{TSx} should be grounded if not used.

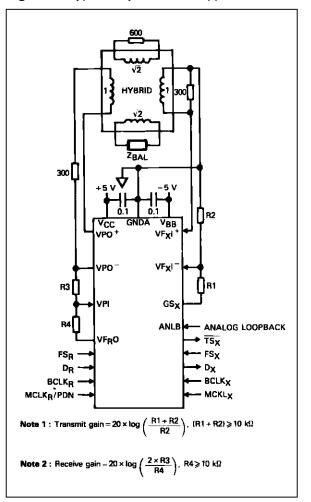
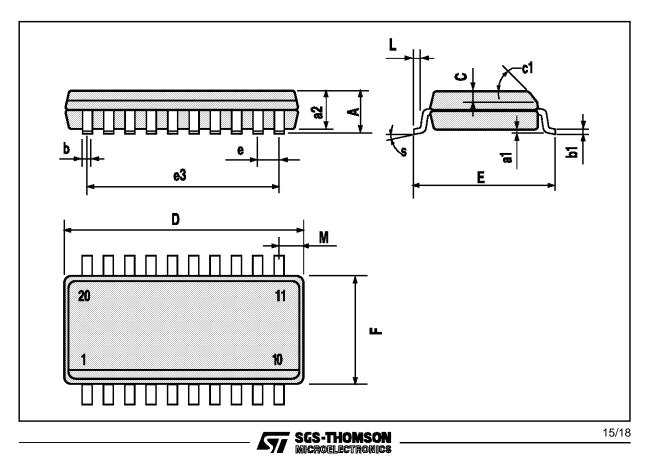


Figure 4 : Typical Asynchronous Application.

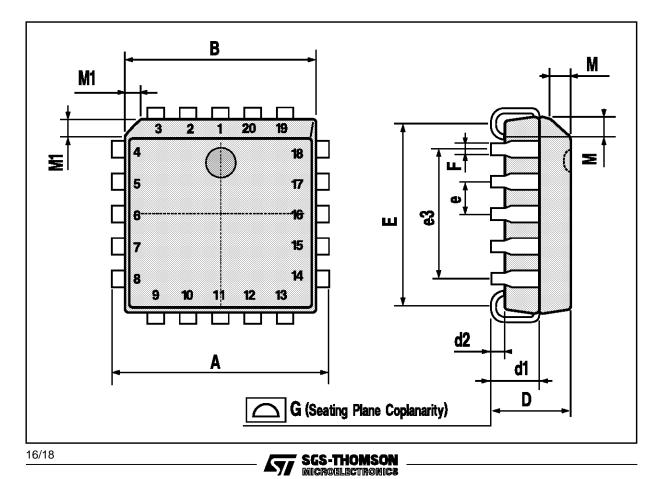
SO20 PACKAGE MECHANICAL DATA

DIM.		mm			inch			
Divi.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.		
А			2.65			0.104		
a1	0.1		0.2	0.004		0.008		
a2			2.45			0.096		
b	0.35		0.49	0.014		0.019		
b1	0.23		0.32	0.009		0.013		
С		0.5			0.020			
c1			45°	(typ.)	•			
D	12.6		13.0	0.496		0.510		
E	10		10.65	0.394		0.419		
e		1.27			0.050			
e3		11.43			0.450			
F	7.4		7.6	0.291		0.300		
L	0.5		1.27	0.020		0.050		
М			0.75			0.030		
S		8° (max.)						



PLCC20 PACKAGE MECHANICAL DATA

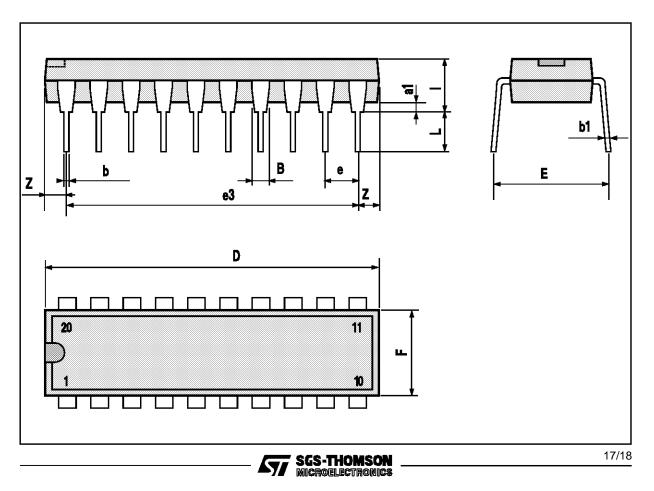
DIM.	mm			inch			
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
А	9.78		10.03	0.385		0.395	
В	8.89		9.04	0.350		0.356	
D	4.2		4.57	0.165		0.180	
d1		2.54			0.100		
d2		0.56			0.022		
E	7.37		8.38	0.290		0.330	
е		1.27			0.050		
e3		5.08			0.200		
F		0.38			0.015		
G			0.101			0.004	
М		1.27			0.050		
M1		1.14			0.045		



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DIP20 PACKAGE MECHANICAL DATA

DIM.	mm			inch			
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
a1	0.254			0.010			
В	1.39		1.65	0.055		0.065	
b		0.45			0.018		
b1		0.25			0.010		
D			25.4			1.000	
E		8.5			0.335		
е		2.54			0.100		
e3		22.86			0.900		
F			7.1			0.280	
I			3.93			0.155	
L		3.3			0.130		
Z			1.34			0.053	



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